### 研究論文

# ソリューションプラズマプロセスによる炭化ケイ素ナノ粒子の合成

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## Synthesis of SiC Nanoparticles by Solution Plasma Process

by

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### **Abstract**

Silicon carbide (SiC) have superior properties such as high hardness, heat resistance, chemical resistance, and chemical stability. Therefore, it is expected to be applied to abrasives, fine ceramics, and semiconductors. Since the solution plasma process (SPP) is generated in a solution, the plasma temperature is low and the plasma is non equilibrium. In addition, a high reaction rate can be realized under atmospheric pressure. In this paper, we report the synthesis and characterization of SiC nanoparticles by SPP using the mixed solution of hexane as carbon source and 4 types of organic silane molecules with different structures as silicon sources. The diameters of the synthesized particles were in the range of several ten nanometers. X-ray diffraction (XRD) patterns and FT-IR spectra showed that all samples were composed of SiC, SiO<sub>2</sub>, and Si. The peak intensity originated from SiC changed due to the structural differences of silicon sources and increased as the number of alkoxy group in the silicon sources decreased. The formation of amorphous SiO<sub>2</sub> at SiC nanoparticle surfaces was promoted when the silicon sources containing alkoxy groups were used. Optical emission spectroscopy (OES) revealed the generation of silicon atom and C<sub>2</sub> radical. It is speculated that SiC is synthesized when these active species collide in the plasma.

Keywords: Silicon carbide, Solution plasma, Nanoparticles

### 1. 緒言

炭化ケイ素は、炭素とケイ素が1:1で結合した化合物で、その結合は共有結合である. 共有結合性が非常に強く、高硬度、熱伝導性、低熱膨張性、耐酸化性、耐熱性、耐摩耗性、化学的安定性といった様々な優れた特徴をもつ. 機械的性質に関してはダイヤモンド、炭化ホウ素に次ぐモース

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硬度をもつ. 耐熱性に関しては 1500℃以上の高温にも耐え,電気的特性に関しては、炭化ケイ素のバンドキャップはシリコンの 2~3 倍であり、絶縁破壊電界強度も高く、また、炭化ケイ素は化学的に安定で耐薬品性に優れ、アルカリや酸にも侵されにくい特徴をもつ <sup>1)</sup>. これらの特徴から、炭化ケイ素は構造材料やパワー半導体として広く利用されている.

近年,炭化ケイ素は,耐摩耗性や耐擦傷性,硬質性などを有する皮膜を形成するための塗料や放熱用フィラー材などの複合材料等の新たな用途への応用が期待されており,特に,ナノサイズの炭化ケイ素への注目は集まっている<sup>2)</sup>.

炭化ケイ素の粒子を作製する方法としては、硅石粉末と 炭素の固相反応が一般的に利用されている.この方法は生 産規模が大きく安価に作製できるが、微細化を行うために 粉砕や解砕、化学処理等のプロセスを必要とするため、平